

N-Channel 30-V (D-S) MOSFET

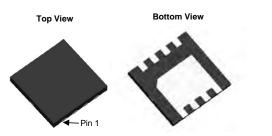
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
30	0.0045 at V _{GS} = 10 V	40	26.5 nC			
30	0.0060 at V _{GS} = 4.5 V	33.3	20.5 IIC			

FEATURES

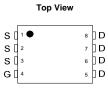
- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

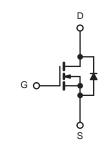
APPLICATIONS

- DC/DC Conversion
 - Low-Side Switch
- Notebook PC
- Gaming



DFN 3x3 EP





N-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	IGS T _A = 25 °C,	unless other	rwise noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		40		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		32.6		
	T _A = 25 °C		31.5 ^{b, c}		
	T _A = 70 °C	1	27.1 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	70	A	
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	5.4		
	T _A = 25 °C	'S	2.7 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	40		
Avalanche Energy		E _{AS}	80	mJ	
	T _C = 25 °C		6.0		
Maximum Power Dissipation	T _C = 70 °C	P _D	3.3	w	
	T _A = 25 °C	ן יי ך	3.0 ^{b, c}		
	T _A = 70 °C	1 T	1.9 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	33	42	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	16	21	C/W	

Notes:

a. Based on $T_C = 25 \text{ °C}$. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85 °C/W.





Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•		•	•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			27			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- Ι _D = 250 μΑ		- 5.6		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.5		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	30			Α	
		V _{GS} = 10 V, I _D = 15 A		0.0045	1 1		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		0.0060		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		75		S	
Dynamic ^b					L	I	
Input Capacitance	C _{iss}			2545		pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		450			
Reverse Transfer Capacitance	C _{rss}	1		140			
	Qg	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A	62				
Total Gate Charge				26.5		nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		8.5			
Gate-Drain Charge	Q _{gd}	1		7.3			
Gate Resistance	Rg	f = 1 MHz	0.2	1.1	2.2	Ω	
Turn-On Delay Time	t _{d(on)}			35	60		
Rise Time	t _r	V _{DD} = 15 V, R _L = 1.5 Ω		16	30		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		48	85		
Fall Time	t _f	1		16	30		
Turn-On Delay Time	t _{d(on)}			18	35	- ns - -	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_{L} = 1.5 \Omega$		8	16		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		41	75		
Fall Time	t _f			8	18		
Drain-Source Body Diode Characteristi	cs		•	•	•		
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			5.4		
Pulse Diode Forward Current ^a	I _{SM}				70	A	
Body Diode Voltage	V _{SD}	I _S = 3 A		0.72	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			33	65	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			27	54	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		17			
Reverse Recovery Rise Time	t _b	1		16		ns	

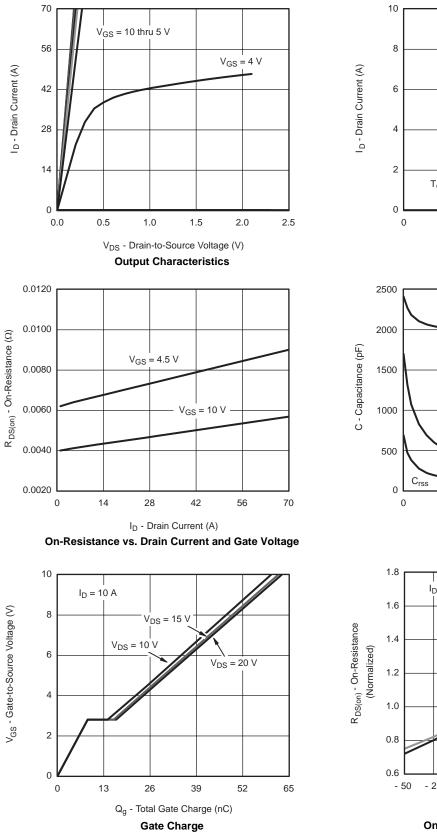
Notes:

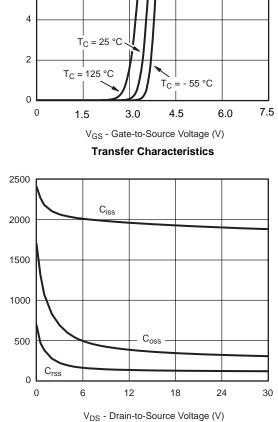
a. Pulse test; pulse width \leq 300 μs , duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

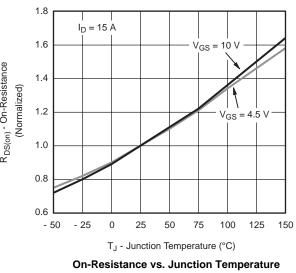








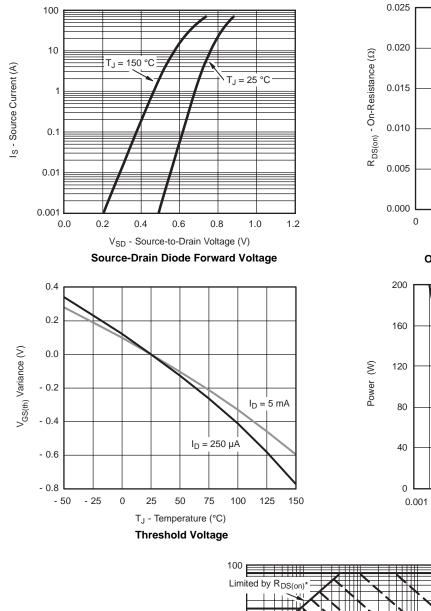




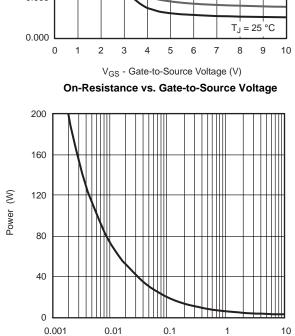


 $I_{D} = 15 \text{ A}$

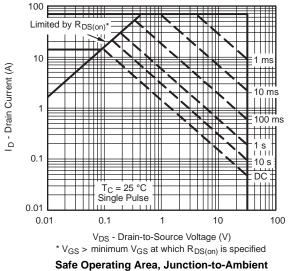
T_J = 125 °C



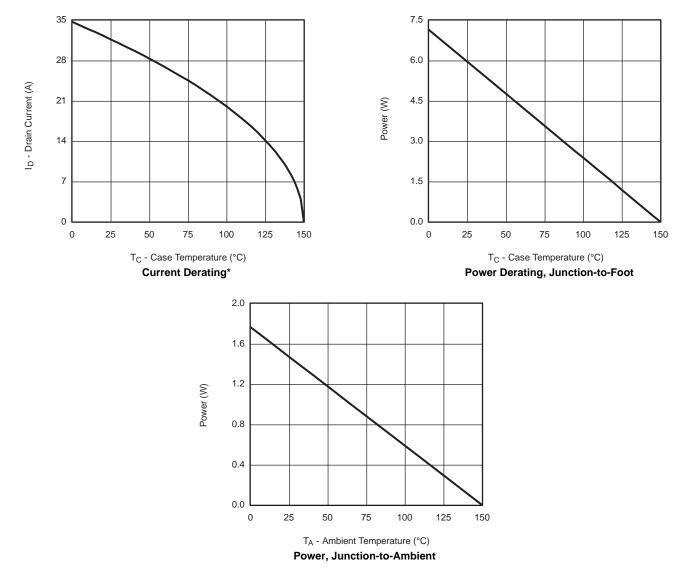
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Time (s)
Single Pulse Power





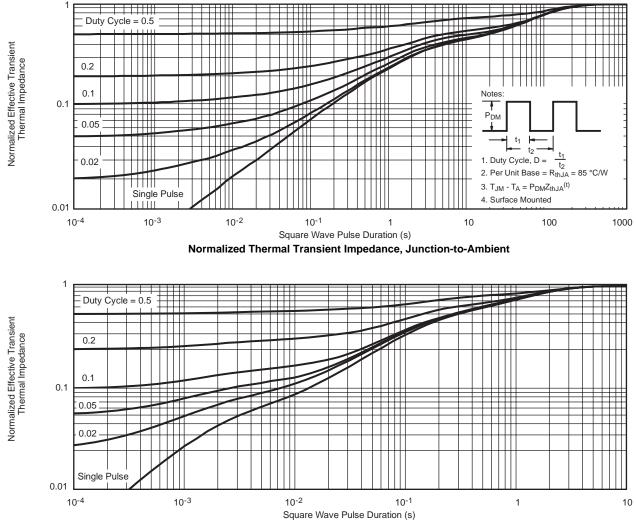


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

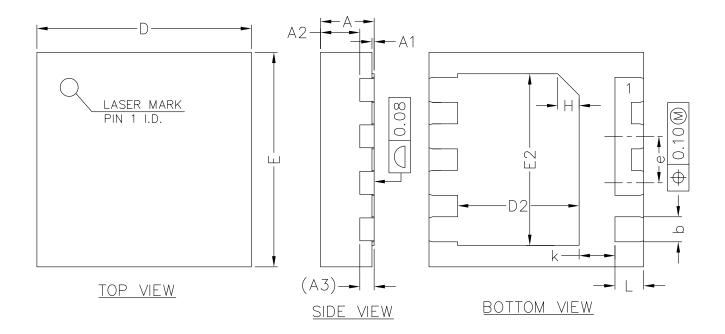






Normalized Thermal Transient Impedance, Junction-to-Foot







<u>SIDE VIEW</u>

(UNITS OF MEASURE=MILLIMETER)					
SYMBOL	MIN	NOM	MAX		
А	0.70	0.75	0.80		
A1	0.00	0.02	0.05		
A2	0.50	0.55	0.60		
A3	0.20REF				
b	0.30	0.35	0.40		
D	2.90	3.00	3.10		
E	2.90	3.00	3.10		
D2	1.60	1.70	1.80		
E2	2.30	2.40	2.50		
е	0.55	0.65	0.75		
K	0.40	0.50	0.60		
L	0.35	0.40	0.45		

COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

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